



B

C

D

E

F

Derating diagram acc. to IEC 60512-5 (Current carrying capacity)

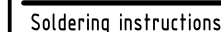
Control and test procedures according to DIN IEC 60512-5



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Below is a table derived from actual experiences

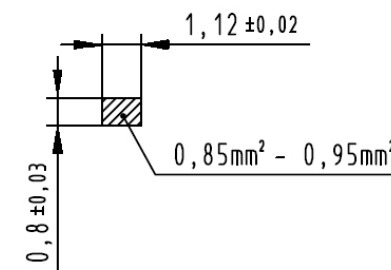


The connectors should be protected when being soldered in a dip, flow or film soldering baths. Otherwise, they might become contaminated as a result of soldering operations or deformed as a result of overheating.

(1) For prototypes and short runs protect the connectors with an industrial adhesive tape, e.g. Tesaband 4331 (www.tesa.de). Cover the underside of the connector moulding and the adjacent parts of the pcb as well as the open sides of the connector. This will prevent heat and gases of the soldering apparatus from damaging the connector. About 140 + 5 mm of the tape should suffice.

(2) For large series a jig is recommended. Its protective cover with a fast action mechanical locking device shields the connectors from gas and heat generated by the soldering apparatus. As an additional protection a foil can be used for covering the parts that should not be soldered.

Cross section of solder pins



Scale
1:1

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e size tol.

Inspected by	TADJE
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Standardisation	HOFFMANN
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Sub. DS 09 0
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State	Final Release
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